



L	Hits	Search Text	DB	Time stamp
Number				
1	594	(257/330).CCLS.	USPAT;	2002/05/16
			US-PGPUB;	10:47
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
2	288	(257/331).CCLS.	USPAT;	2002/05/16
			US-PGPUB;	11:04
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	547	(257/341).CCLS.	USPAT;	2002/05/16
			US-PGPUB;	11:05
			EPO; JPO;	
1			DERWENT;	
			IBM TDB	



L	Hits	Search Text	DB	Time stamp
Number				
1	258	(257/343).CCLS.	USPAT;	2002/05/16
			US-PGPUB;	13:07
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
2	691	(257/329, 332, "333").ccls.	USPAT;	2002/05/16
			US-PGPUB;	13:08
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

L	Hits	Search Text	DB	Time stamp
Number				
1	0	semiconductor and (plateable adj metal)	USPAT;	2002/05/16
		and gate	US-PGPUB;	14:13
		-	EPO; JPO;	
			DERWENT;	
			IBM TDB	
2	8204	semiconductor and plat\$4 and metal and	USPAT;	2002/05/16
		(gate adj electrode)	US-PGPUB;	14:17
		, ·-	EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	226	(semiconductor and plat\$4 and metal and	USPAT;	2002/05/16
		(gate adj electrode)) and (plat\$4 adj	US-PGPUB;	14:20
		metal)	EPO; JPO;	
			DERWENT;	
			TBM TDB	